ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16727D

Generic Copy

Issue Date: 05-Mar-2014

TITLE: Copper Wire Bond for NCP5500 and NCV5500

PROPOSED FIRST SHIP DATE: 05-Jun-2014

AFFECTED CHANGE CATEGORY(S): Assembly Process

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <alan.garlington@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <tomas.vajter@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

Copper Wire has been qualified for use in two part numbers in the SOIC8 package assembled at the ON Semiconductor factory located in Carmona, Philippines. The SOIC 8 line has been qualified previously to run Copper wire (FPCN 16727) in Sept 2011. These two devices were delayed and not included on the original list of devices.

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RELIABILITY DATA SUMMARY:

Reliability Test Results: Qualification vehicle - NCP5500DADJR2G

Test	Name	Conditions	Test	Lot A	Lot B	Lot C	Control
HTOL	High Temp Op Life	+150C	504 Hrs	0/80	0/80	0/80	0/80
HTSL	High Temp Storage Life	+150C	504 Hrs	0/80	0/80	0/80	0/80
PC	Pre Conditioning	MSL1	3x IR @ 260C	0/240	0/240	0/240	0/240
TC-PC	Temp Cycle	-65C to +150C	1000 cyc	0/80	0/80	0/80	0/80
HAST-PC	Highly Accel Stress Testing	+130C; RH 85% 28 psig	96 Hrs	0/80	0/80	0/80	0/80
AC-PC	Autoclave	+121C; RH = 100% Psig = 15	96 Hrs	0/80	0/80	0/80	0/80
CDPA1	Custom Dest. Phy Analysis	Wire Pull @ 96 Hrs HAST	Min 3 Gms	0/5	0/5	0/5	0/5
CDPA1	Custom Dest. Phy Analysis	Wire Pull @ 1008 Hrs HTOL	Min 3 Gms	0/5	0/5	0/5	0/5
RSH	Resistance to Solder Heat	260C Immersion	C= 0	0/30	0/30	0/30	0/30

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no electrical characterization difference in products assembled with Copper Wire.

CHANGED PART IDENTIFICATION:

Parts assembled with Copper wire can be identified by the marking date code. Conversion will not occur until after expiration of this FPCN approximately WW1418.

List of affected General Parts:

NCP5500DADJR2G
NCV5500DADJR2G